SUA-45-S4

Universal Heatsink, 45-Watt Power Dissipation Capacity

SUA-45-S4 is a universal heatsink, which is designed and fabricated for Eravant's active device applications with up to 45-Watt power dissipation. The heatsink consists of the main heatsink body, a DC fan, and a heat spreader. The heat spreader is also known as an adapter, which is used to bridge the mounting gap between the heat sink main body and the to-be-heat-sunk devices, such as power amplifier, frequency active multiplier, oscillator, transmitter, and transceiver due to various mounting hole locations. The heat spreader offers various mounting patterns for Eravant's "**-E3**" lineup of amplifiers. This heatsink is not only designed for Eravant's standard products, but also for many industrial standard microwave and millimeter wave products offered by other manufacturers. Other heatsinks with different power dissipation capacities are offered under different model numbers.

Electrical Specifications:

Item	Specification
Fan Power	+12 Vdc
Fan Power Designations	Red Lead (Positive); Black Lead (GND); Yellow Lead (N/A or Tach)
DC Connector	Molex 5051-03
Fan Detachability	Yes

Mechanical Specifications:

Item	Specification
Mounting Screw	4-40 x ¼" Long, 4 Pieces
Material	Aluminum
Finish	Clear Chem Film
Weight	8.4 Oz
Dimensions	2.36" (W) x 2.36" (L) x 2.52" (H)
Outline	UA-45-4

ECCN

EAR99

FEATURES

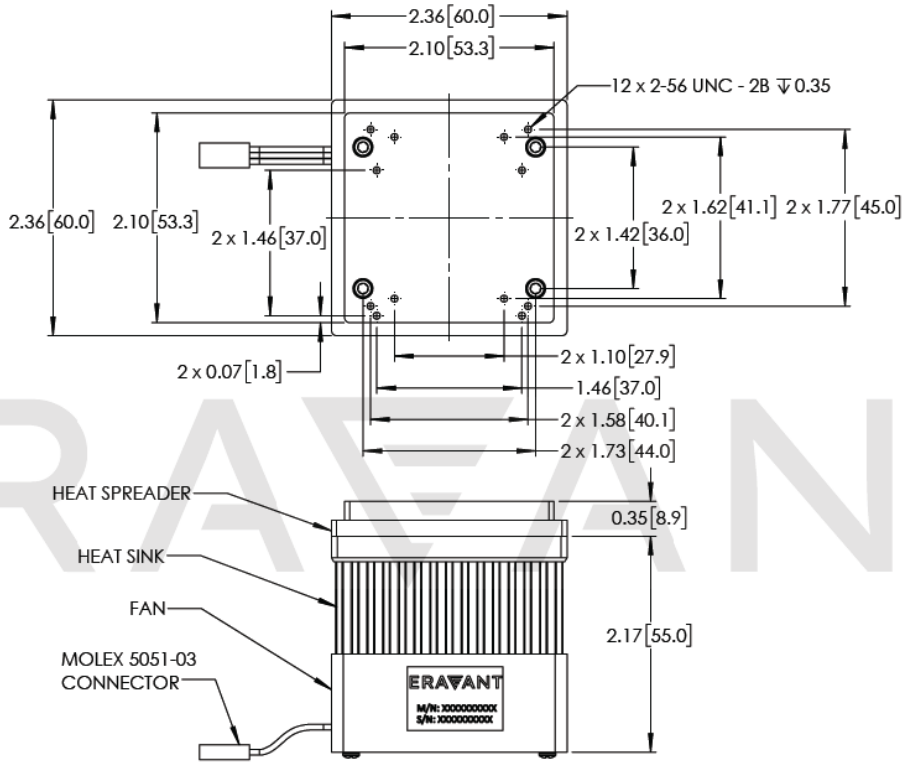
- High Power Dissipation Efficiency
- DC Powered Cooling Fan
- Heat Spreader for Various Mounting Patterns
- Easy Mounting and Dismounting

APPLICATIONS

- Single Function Components
- Sub-assemblies
- Lab Use

SUPPLEMENTAL DETAILS

Mechanical Outline: (Unless otherwise specified, all dimensions are in inches [millimeters])



MOLEX 5051-03	
WIRE	**SIGNAL**
BLACK	GND
RED	+12 VDC

CAUTION:

- Remove the heat spreader from the heatsink by unscrewing the four provided 4-40 mouting screws.
- Mount the heat spreader onto the to-be-heat-sunk-device by inserting 2-56 screws from the slotted surface to form the sub-assembly. Apply heat compound material between the two surfaces for better heatsink efficiency.
- Remount the sub-assembly onto the heatsink main body. Apply heat compound material if desired.

NOTE:

- Eravant reserves the right to change the information presented without notice.